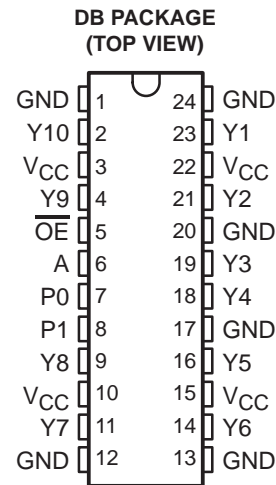


# CDC2351-EP 1-LINE TO 10-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

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- **Controlled Baseline**
  - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications**
- **Operates at 3.3-V V<sub>CC</sub>**
- **LVTTL-Compatible Inputs and Outputs**
- **Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)**
- **Distributes One Clock Input to 10 Outputs**
- **Outputs Have Internal Series Damping Resistor to Reduce Transmission Line Effects**
- **Distributed V<sub>CC</sub> and Ground Pins Reduce Switching Noise**
- **State-of-the-Art EPIC-II B™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Shrink Small-Outline (DB) Package**

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



## description

The CDC2351 is a high-performance clock-driver circuit that distributes one input (A) to 10 outputs (Y) with minimum skew for clock distribution. The output-enable ( $\overline{OE}$ ) input disables the outputs to a high-impedance state. Each output has an internal series damping resistor to improve signal integrity at the load. The CDC2351 operates at nominal 3.3-V V<sub>CC</sub>.

The propagation delays are adjusted at the factory using the P0 and P1 pins. The factory adjustments ensure that the part-to-part skew is minimized and is kept within a specified window. Pins P0 and P1 are not intended for customer use and should be connected to GND.

The CDC2351M is characterized for operation over the full military temperature range of –55°C to 125°C.

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SSOP – DB    Tape and Reel	CDC2351MDBREP	CK2351MEP

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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# CDC2351-EP

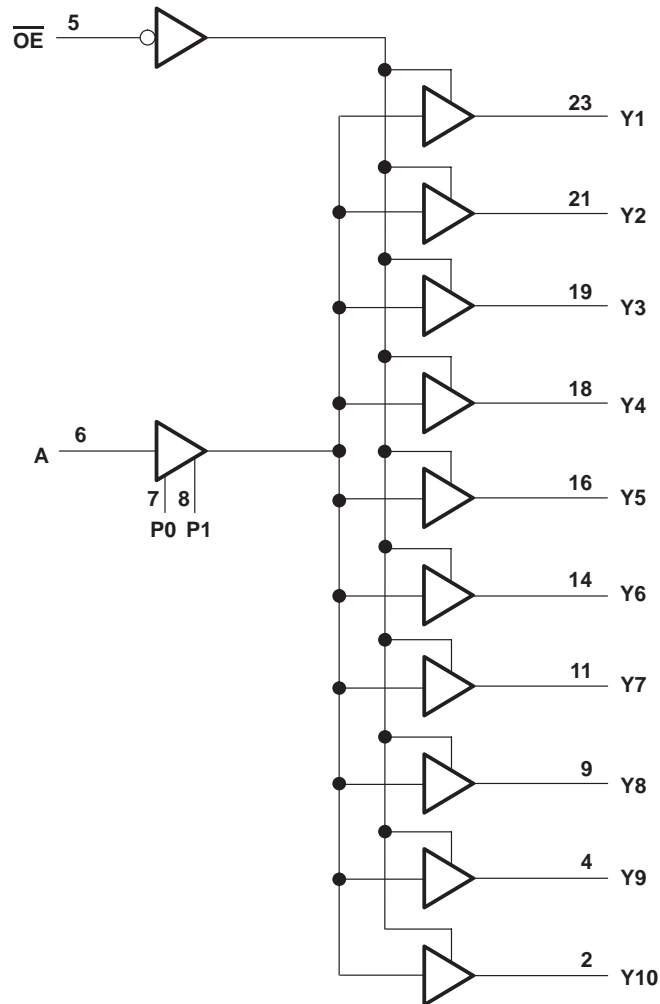
## 1-LINE TO 10-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

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FUNCTION TABLE

INPUTS		OUTPUTS
A	$\overline{OE}$	In
L	H	Z
H	H	Z
L	L	L
H	L	H

logic diagram (positive logic)



# CDC2351-EP 1-LINE TO 10-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	–0.5 V to 4.6 V
Input voltage range, $V_I$ (see Note 1) .....	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, $V_O$ (see Note 1) .....	–0.5 V to 3.6 V
Current into any output in the low state, $I_O$ .....	24 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	–18 mA
Output clamp current, $I_{OK}$ ( $V_I < 0$ ) .....	–50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DB package .....	0.65 W
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, see the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.

## recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	3	3.6	V
$V_{IH}$	High-level input voltage	2		V
$V_{IL}$	Low-level input voltage		0.8	V
$V_I$	Input voltage	0	5.5	V
$I_{OH}$	High-level output current		–12	mA
$I_{OL}$	Low-level output current		12	mA
$f_{clock}$	Input clock frequency		100	MHz
$T_A$	Operating free-air temperature	–55	125	°C
		CDC2351M		

NOTE 3: Unused pins (input or I/O) must be held high or low.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
$V_{IK}$	$V_{CC} = 3\text{ V}$ ,	$I_I = -18\text{ mA}$			–1.2	V
$V_{OH}$	$V_{CC} = 3\text{ V}$ ,	$I_{OH} = -12\text{ mA}$	2			V
$V_{OL}$	$V_{CC} = 3\text{ V}$ ,	$I_{OL} = 12\text{ mA}$			0.8	V
$I_I$	$V_{CC} = 3.6\text{ V}$ ,	$V_I = V_{CC}$ or GND			±1	μA
$I_O^\ddagger$	$V_{CC} = 3.6\text{ V}$ ,	$V_O = 2.5\text{ V}$	–7		–70	mA
$I_{OZ}$	$V_{CC} = 3.6\text{ V}$ ,	$V_{CC} = 3\text{ V}$ or 0			±10	μA
$I_{CC}$	$V_{CC} = 3.6\text{ V}$ ,	$I_O = 0$ , $V_I = V_{CC}$ or GND	Outputs high		0.3	mA
			Outputs low		15	
			Outputs disabled		0.3	
$C_i$	$V_I = V_{CC}$ or GND,	$V_{CC} = 3.3\text{ V}$ ,	$f = 10\text{ MHz}$		4	pF
$C_o$	$V_O = V_{CC}$ or GND,	$V_{CC} = 3.3\text{ V}$ ,	$f = 10\text{ MHz}$		6	pF

‡ Not more than one output should be tested at a time and the duration of the test should not exceed one second.



**CDC2351-EP**  
**1-LINE TO 10-LINE CLOCK DRIVER**  
**WITH 3-STATE OUTPUTS**

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**switching characteristics,  $C_L = 50$  pF (see Figure 1 and Figure 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$			$V_{CC} = 3$ V to 3.6 V, $T_A = -55^\circ\text{C}$ to $125^\circ\text{C}$		UNIT
			MIN	TYP	MAX	MIN	MAX	
$t_{PLH}$	A	Y	3.8	4.3	4.8	1.1	11	ns
$t_{PHL}$			3.6	4.1	4.6	1	9.7	
$t_{PZH}$	$\overline{OE}$	Y	2.4	4.9	6	1	12	ns
$t_{PZL}$			2.4	4.3	6	1	11.1	
$t_{PHZ}$	$\overline{OE}$	Y	2.2	4.4	6.3	1	11.1	ns
$t_{PLZ}$			2.2	4.6	6.3	1	11.5	
$t_{sk(o)}$	A	Y	0.3 0.5		2.5		ns	
$t_{sk(p)}$	A	Y	0.2 0.8		3		ns	
$t_{sk(pr)}$	A	Y	1				ns	
$t_r$	A	Y			2.5		ns	
$t_f$	A	Y			2.5		ns	

**switching characteristics temperature and  $V_{CC}$  coefficients over recommended operating free-air temperature and  $V_{CC}$  range (see Note 4)**

PARAMETER		FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$\infty t_{PLH}(T)$	Average temperature coefficient of low-to-high propagation delay	A	Y	85 <sup>†</sup>		ps/10°C
$\infty t_{PHL}(T)$	Average temperature coefficient of high-to-low propagation delay	A	Y	50 <sup>†</sup>		ps/10°C
$\infty t_{PLH}(V_{CC})$	Average $V_{CC}$ coefficient of low-to-high propagation delay	A	Y	-145 <sup>‡</sup>		ps/ 100 mV
$\infty t_{PHL}(V_{CC})$	Average $V_{CC}$ coefficient of high-to-low propagation delay	A	Y	-100 <sup>‡</sup>		ps/ 100 mV

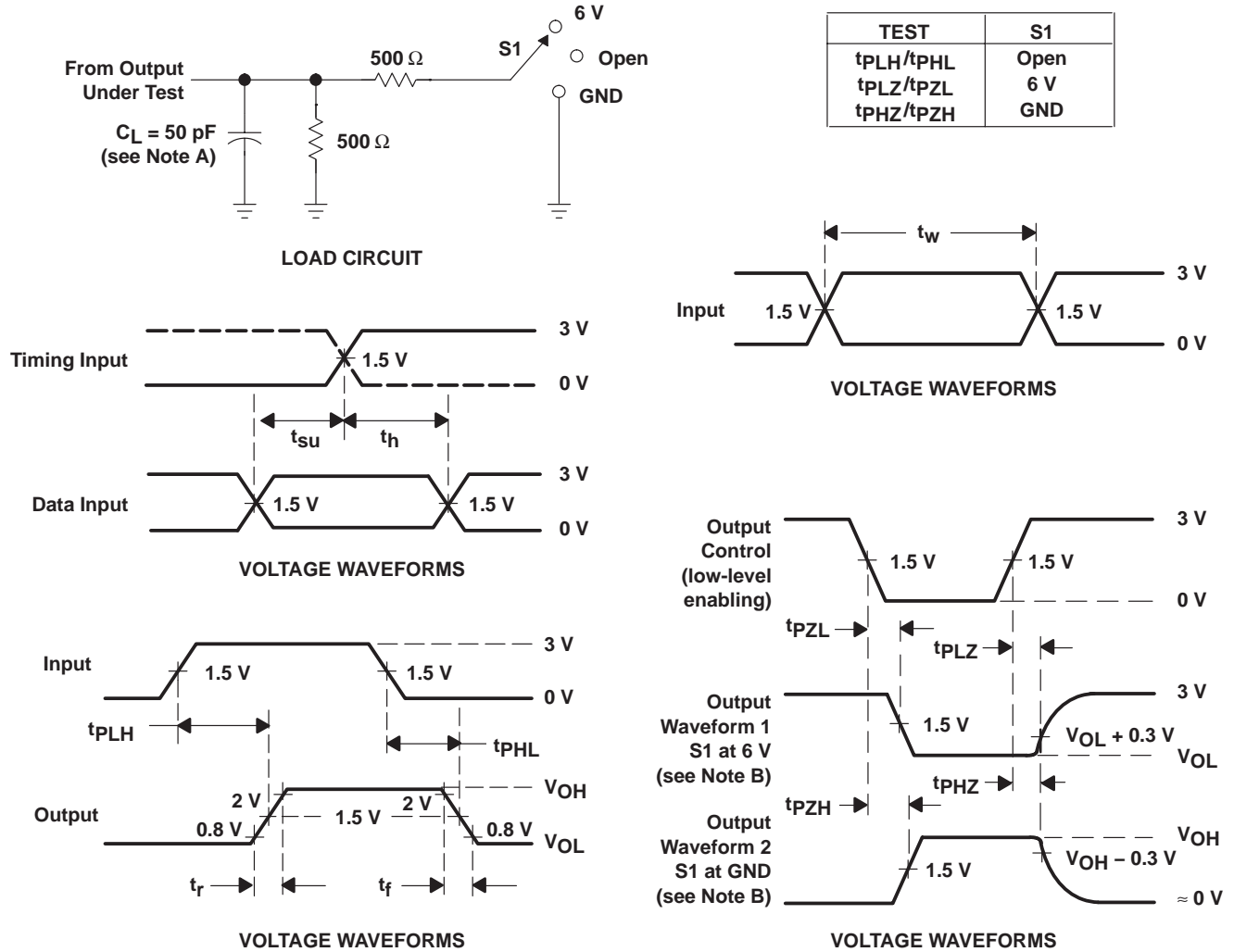
<sup>†</sup>  $\infty t_{PLH}(T)$  and  $\infty t_{PHL}(T)$  are virtually independent of  $V_{CC}$ .

<sup>‡</sup>  $\infty t_{PLH}(V_{CC})$  and  $\infty t_{PHL}(V_{CC})$  are virtually independent of temperature.

NOTE 4: This data was extracted from characterization material and has not been tested at the factory.



**PARAMETER MEASUREMENT INFORMATION**



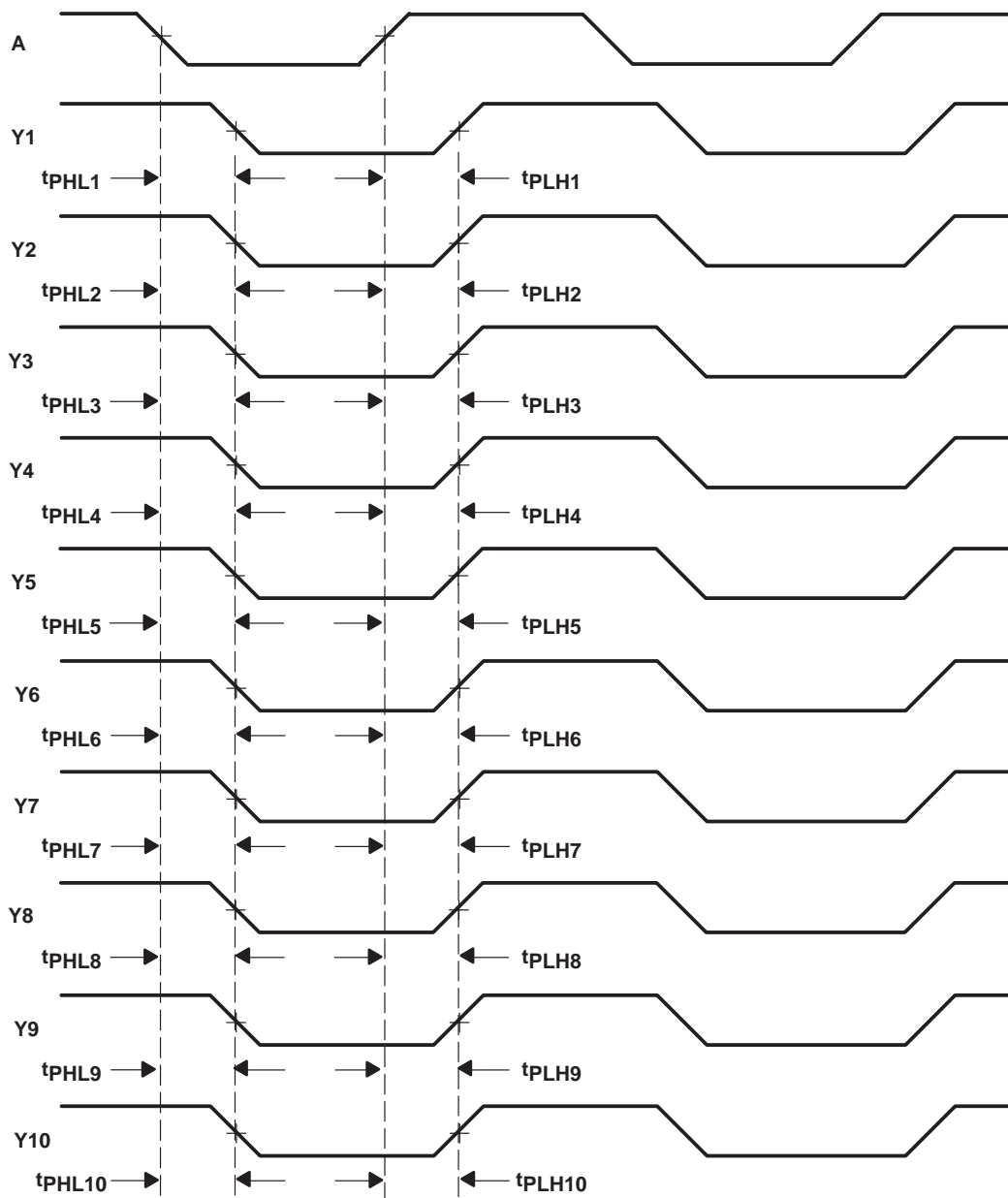
- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .  
 D. The outputs are measured one at a time with one transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

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**PARAMETER MEASUREMENT INFORMATION**



- NOTES: A. Output skew,  $t_{sk(o)}$ , is calculated as the greater of:
- The difference between the fastest and slowest of  $t_{PLHn}$  ( $n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10$ )
  - The difference between the fastest and slowest of  $t_{PHLn}$  ( $n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10$ )
- B. Pulse skew,  $t_{sk(p)}$ , is calculated as the greater of  $|t_{PLHn} - t_{PHLn}|$  ( $n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10$ ).
- C. Process skew,  $t_{sk(pr)}$ , is calculated as the greater of:
- The difference between the fastest and slowest of  $t_{PLHn}$  ( $n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10$ ) across multiple devices under identical operating conditions.
  - The difference between the fastest and slowest of  $t_{PHLn}$  ( $n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10$ ) across multiple devices under identical operating conditions.

**Figure 2. Waveforms for Calculation of  $t_{sk(o)}$ ,  $t_{sk(p)}$ ,  $t_{sk(pr)}$**



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CDC2351MDBREP	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CDC2351MDBREPG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
V62/04757-01XE	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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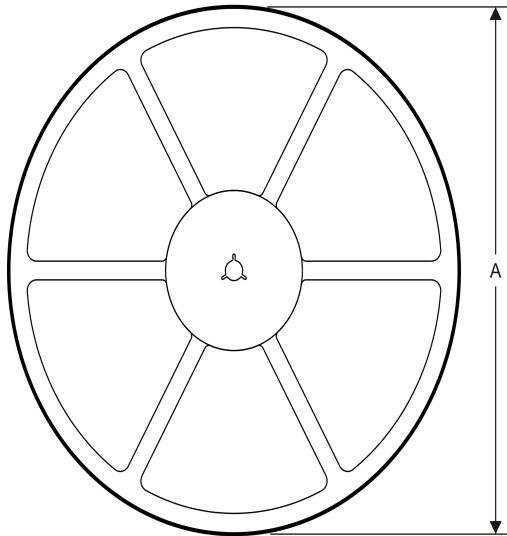
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- Catalog: [CDC2351](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC2351MDBREP	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC2351MDBREP	SSOP	DB	24	2000	367.0	367.0	38.0

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